

17. (new) A solder coated material as claimed in claim 16 wherein the difficult to solder material is an iron-nickel alloy.

18. (new) A solder coated material as claimed in claim 16 wherein the material having excellent solderability is selected from gold, silver, copper, tin, nickel, and solder alloys.

19. (new) A solder coated material as claimed in claim 18 wherein the material having excellent solderability is a tin-silver alloy.

20. (new) A portion to be soldered of an electronic part comprising a substrate comprising a difficult to solder material, an electroplated layer of a material having excellent solderability and having a thickness of 0.5 - 5 micrometers applied as base plating atop the substrate, and a hot dip solder plating layer with a thickness of 10 - 50 micrometers applied atop the electroplated layer.

21. (new) A portion to be soldered of an electronic part as claimed in claim 20 wherein the difficult to solder material is an iron-nickel alloy.

22. (new) A portion to be soldered of an electronic part as claimed in claim 20 wherein the material having excellent solderability is selected from gold, silver, copper, tin, nickel, and solder alloys.

23. (new) A portion to be soldered of an electronic part as claimed in claim 22 wherein the material having excellent solderability is a solder alloy of a tin-silver alloy.

24. (new) A portion to be soldered of an electronic part as claimed in claim 20 wherein the portion to be soldered is a lead frame for an electronic part, a lid of a packaged electronic part, a battery terminal, a shield of a module, or a connector for a surface mounted part.

25. (new) A manufacturing method for a solder coated material comprising electroplating a difficult to solder material with a material having excellent solderability to form an electroplated layer, and then passing the difficult to solder material through a molten solder bath and adhering molten solder to the electroplated layer.

26. (new) A manufacturing method for a solder coated material as claimed in claim 25 including applying ultrasonic waves to the molten solder bath.

27. (new) A manufacturing method for a solder coated material as claimed in claim 25 wherein the difficult to solder material is an iron-nickel alloy.

28. (new) A manufacturing method for a solder coated material as claimed in claim 25 wherein the material having

excellent solderability is selected from gold, silver, copper, tin, nickel, and solder alloys.

29. (new) A manufacturing method for a solder coated material as claimed in claim 25 wherein the molten solder bath is maintained in an inert atmosphere.

30. (new) A manufacturing method for a solder coated material as claimed in claim 25 wherein the molten solder bath in the molten solder is a wave soldering bath.

REMARKS

In this amendment, original claims 1 - 15 have been replaced by new claims 16 - 30. The original claims were a translation of Japanese claims. The new claims employ a writing style more typical of United States patent applications (for example, "characterized by" has been changed to "wherein") and delete multiple dependencies so as to reduce filing fees. The changes to the claims are in no way related to issues of patentability.